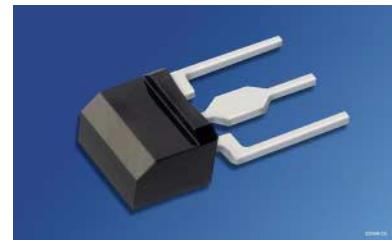


# Doppel-NPN-Silizium-Fototransistor mit Tageslichtsperrfilter Dual Silicon NPN Phototransistor with Daylight-Cutoff Filter Lead (Pb) Free Product - RoHS Compliant

SFH 3162 F



Nicht für Neuentwicklung / Not for new design

## Wesentliche Merkmale

- Tageslichtsperrfilter
- Doppel-Fototransistor nebeneinander positioniert
- Doppel-Fototransistor mit gemeinsamem Kollektor
- Optimale Kombination mit SFH4113 (horizontaler Enkoder)

## Features

- Daylight Filter
- Dual Phototransistor positioned side by side
- Dual Phototransistor with common Collector
- Ideal combination with SFH4113 (horizontal encoder)

## Anwendungen

- Richtungserkennung
- Empfänger in Lichtschranken
- Bandende-Erkennung (z.B. Videorecorder)
- Positionsüberwachung
- Barcode-Leser
- „Messen/Steuern/Regeln“
- Münzzähler

## Applications

- Direction detection
- Detector in photointerrupters
- Tape end detection
- Position sensing
- Barcode reader
- For control and drive circuits
- Coin counters

Typ Type	Bestellnummer Ordering Code	$I_{ce(on)}$ [ $\mu A$ ] ( $V_{ce}=3.5V$ , 950nm, $E_e=0.34mW/cm^2$ )
SFH 3162 F	Q62702P5297	185 ... 585

**Grenzwerte****Maximum Ratings**

<b>Bezeichnung Parameter</b>	<b>Symbol Symbol</b>	<b>Wert Value</b>	<b>Einheit Unit</b>
Betriebs- und Lagertemperatur Operating and storage temperature range	$T_{op}; T_{stg}$	- 40 ... + 85	°C
Löttemperatur bei Tauchlötzung Lötstelle $\geq$ 2 mm vom Gehäuse, Lötzeit $t \leq 5$ s Dip soldering temperature $\geq$ 2 mm distance from case bottom, soldering time $t \leq 5$ s	$T_s$	260	°C
Löttemperatur bei Kolbenlötzung Lötstelle $\geq$ 2 mm vom Gehäuse, Lötzeit $t \leq 3$ s Iron soldering temperature $\geq$ 2 mm distance from case bottom, soldering time $t \leq 3$ s	$T_s$	300	°C
Kollektor-Emitterspannung Collector-emitter voltage	$V_{CE}$	30	V
Kollektorstrom Collector current	$I_C$	10	mA
Kollektorspitzenstrom, $t < 10 \mu\text{s}$ Collector surge current	$I_{CS}$	20	mA
Emitter-Kollektorspannung Emitter-collector voltage	$V_{EC}$	7	V
Verlustleistung, $T_A = 25$ °C Total power dissipation	$P_{tot}$	100	mW
Wärmewiderstand Sperrsicht - Umgebung Thermal resistance junction - ambient	$R_{thJA}$	450	K/W

**Kennwerte ( $T_A = 25^\circ\text{C}$ ,  $\lambda = 950 \text{ nm}$ )****Characteristics**

<b>Bezeichnung Parameter</b>	<b>Symbol Symbol</b>	<b>Wert Value</b>	<b>Einheit Unit</b>
Wellenlänge der max. Fotoempfindlichkeit Wavelength of max. sensitivity	$\lambda_{S_{\max}}$	920	nm
Spektraler Bereich der Fotoempfindlichkeit $S = 10\%$ von $S_{\max}$ Spectral range of sensitivity $S = 10\%$ of $S_{\max}$	$\lambda$	780 ... 1100	nm
Abmessungen der Chip-Fläche Dimension of chip area	$L \times B$ $L \times W$	$1.23 \times 0.66$	mm $\times$ mm
Bestrahlungsempfindliche Fläche Radiant sensitive area	$A$	$2 \times 0.15$	mm $^2$
Halbwinkel Half angle	$\phi$	$\pm 75$	Grad deg.
Kapazität Capacitance $V_{CE} = 3V, f = 1 \text{ MHz}, E = 0$	$C_{CE}$	3.2	pF
Dunkelstrom Dark current $V_{CE} = 10 \text{ V}$	$I_{CEO}$	0.1 ( $\leq 100$ )	nA
Fotostrom Photocurrent $E_e = 0.34 \text{ mW/cm}^2, V_{CE} = 3.5 \text{ V}$	$I_{e(on)}^{1)}$	185 .... 585	$\mu\text{A}$
Temperaturkoeffizient von $I_{e(on)}$ Temperature coefficient of $I_{e(on)}$ $V_{ce} = 5 \text{ V}$	$TC$	+ 0.9	%/K

1)  $I_{e(on)}$  ist der Mittelwert der Emitterströme der beiden Phototransistoren. $I_{e(on)}$  is the mean value of the emitter currents of the two phototransistors.

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Emitterstrom-Verhältnis der 2 Fototransistoren Emitter current ratio of the 2 phototransistors $V_{eco} = 3.5V, E_e = 0.34mW/cm^2$	$R^1)$	1 ... 1.1	
Übersprechen zwischen T1 und T2 Crosstalk between T1 and T2 $E_e = 0.34 \text{ mW/cm}^2, \lambda = 950\text{nm}, V_{CE} = 3.5 \text{ V}$	$(Ie1 - Ie1')/Ie1^2)$	3	%
Anstiegszeit/Abfallzeit Rise and fall time $I_C = 1 \text{ mA}, V_{CC} = 5 \text{ V}, R_L = 1 \text{ k}\Omega$	$t_r$ $t_f$	11 11	$\mu\text{s}$
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage $I_C = 50\mu\text{A},$ $E_e = 0.5 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	$V_{CESat}$	0.1 ( $\leq 0.4$ )	V

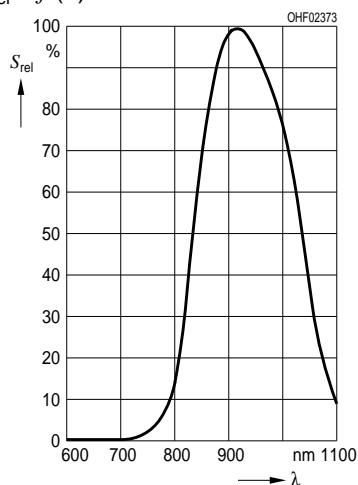
<sup>1)</sup>  $Ie(\text{max})/Ie(\text{min})$

<sup>2)</sup> Testing condition

- a)  $Ie1$  measured while the emitter of T2 is grounded
- b)  $Ie1'$  is the  $Ie1$  reading while the emitter of T2 is not connected

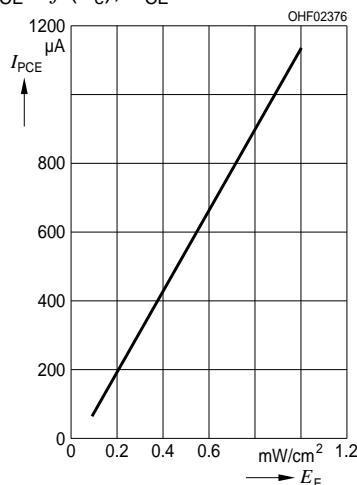
**Relative Spectral Sensitivity**

$$S_{\text{rel}} = f(\lambda)$$



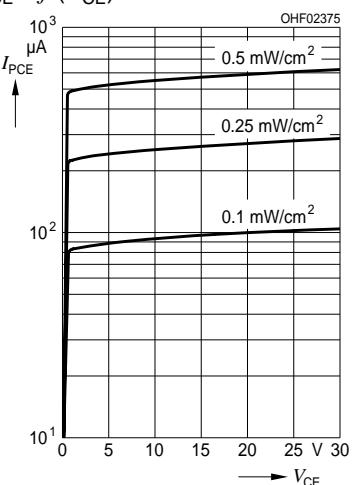
**Photocurrent**

$$I_{\text{PCE}} = f(E_e), V_{\text{CE}} = 5 \text{ V}$$



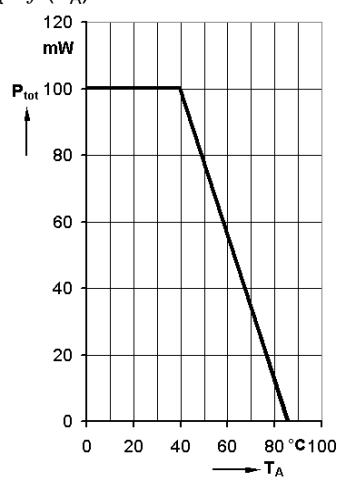
**Photocurrent**

$$I_{\text{PCE}} = f(V_{\text{CE}})$$



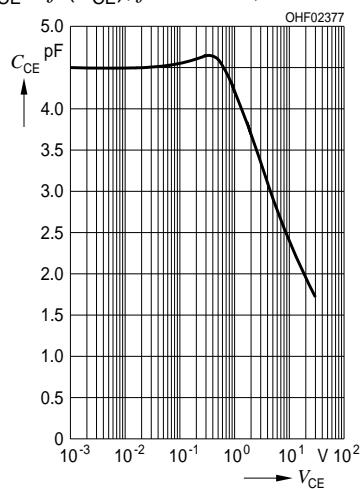
**Total Power Dissipation**

$$P_{\text{tot}} = f(T_A)$$

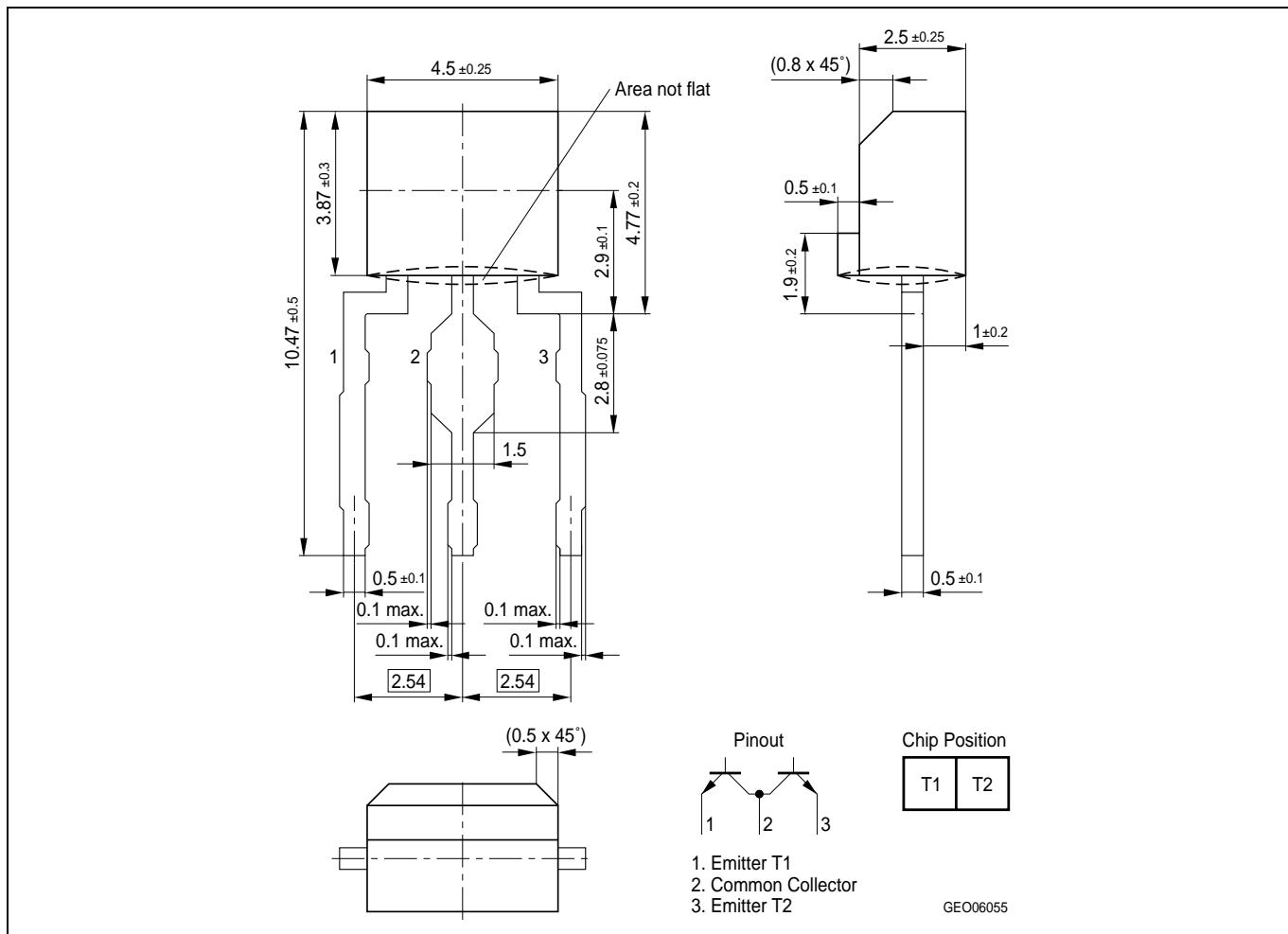


**Collector-Emitter Capacitance**

$$C_{\text{CE}} = f(V_{\text{CE}}), f = 1 \text{ MHz}, E = 0$$

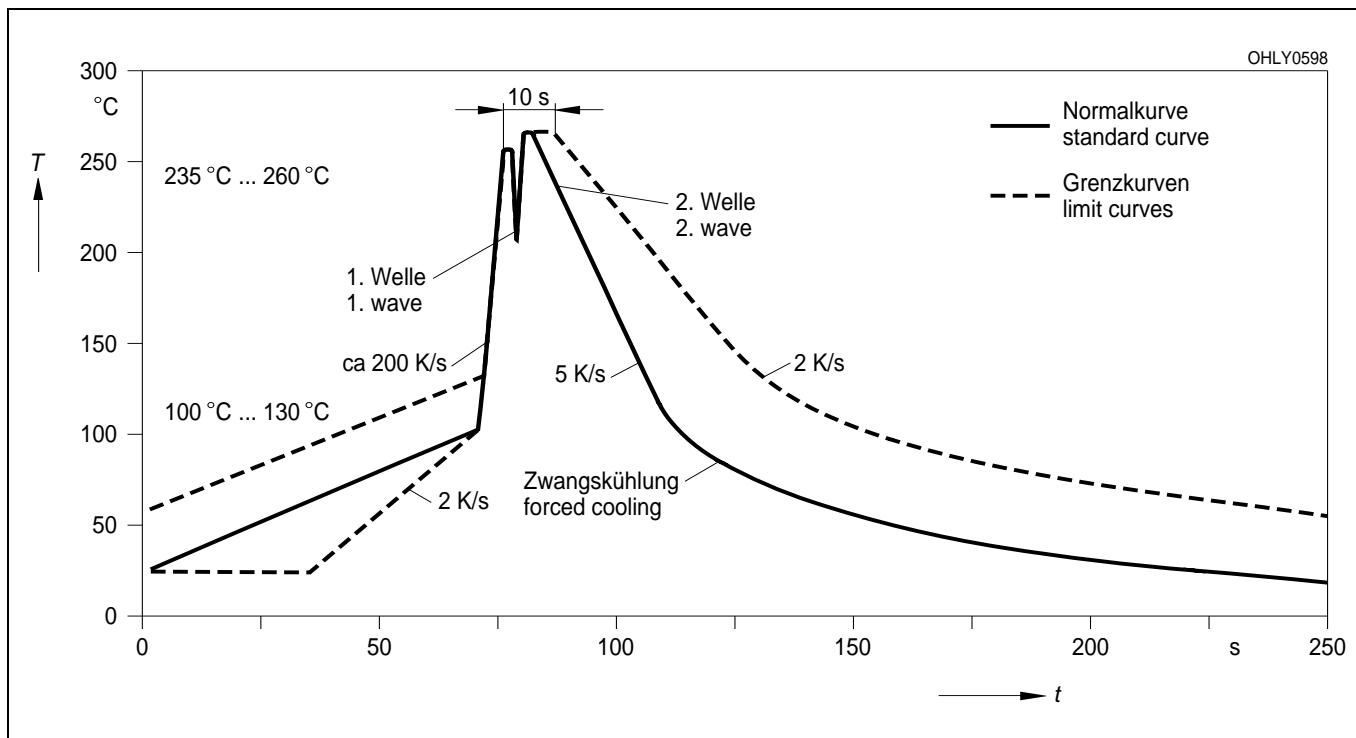


**Maßzeichnung**  
**Package Outlines**



**Lötbedingungen**  
**Soldering Conditions**  
**Wellenlöten (TTW)**  
**TTW Soldering**

(nach CECC 00802)  
 (acc. to CECC 00802)



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